

**METHOD AND PACKAGING STRUCTURE FOR OPTIMIZING WARPAGE
OF FLIP CHIP ORGANIC PACKAGES**

ABSTRACT OF THE DISCLOSURE

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An electronic packaging structure and method of forming thereof wherein the structure is constituted of a modular arrangement which reduces stresses generated in a chip, underfill, and ball grid array connection with a flexible substrate in the form of an organic material, which stresses may result in potential delamination due to thermally-

10

induced warpage between the components of the modular arrangement.